IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Prior Application: J. TANAKA et al et al

Serial No. 10/179,214 Filed: June 26, 2002

Group Art Unit:

Examiner:

For:

خنسر

2815

S. Clark

RESIN-ENCAPSULATED SEMICONDUCTOR APPARATUS AND PROCESS FOR ITS

FABRICATION

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents Alexandria, VA 22314

Sir:

In accordance with the duty of disclosure, Applicants inform the Examiner of the documents cited during prosecution of the parent application, USSN 10/179,214.

This is a continuation application of U.S. Serial No. 10/179,214, filed on June 26, 2002, which is a continuation application of U.S. Serial No. 09/969,847, filed October 4, 2001, now U.S. Patent No. 6,465,827, which is a continuation application of U.S. Serial No. 09/689,802, filed October 13, 2000, now U.S. Patent No. 6,441,416, which is a continuation application of U.S. Serial No. 09/665,062, filed September 19, 2000, abandoned, which is a divisional application of U.S. Serial No. 09/012,104, filed January 22, 1998, now U.S. Patent No. 6,147,374. This application is related to application Serial No. 09/969,848, filed October 4, 2001, now U.S. Patent No. 6,525,359, from which priority is claimed under 35 U.S.C. § 120.

The applicants request the Examiner to initial and return a copy of the attached PTO-1449 form as an indication that the references have been considered.

Respectfully submitted,

John R. Mattingly

Registration No. 20/293 Attorney for Applicant(s)

MATTINGLY, STANGER & MALUR 1800 Diagonal Road, Suite 370 Alexandria, Virginia 22314 (703) 684-1120

Date: September 29, 2003

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